







PCN Number:	20180627001	PCN Date:	June 28, 2018												
Title:	Leadframe Die Pad Offset change for Select SOIC package Devices														
Customer Contact:	PCN Manager	Dept:	Quality Services												
Proposed 1st Ship Date:	Dec 28, 2018	Estimated Sample Availability:	Provided upon Request												
Change Type:															
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design												
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet												
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change												
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site												
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process												
		<input type="checkbox"/>	Wafer Bump Site												
		<input type="checkbox"/>	Wafer Bump Material												
		<input type="checkbox"/>	Wafer Bump Process												
		<input type="checkbox"/>	Wafer Fab Site												
		<input type="checkbox"/>	Wafer Fab Materials												
		<input type="checkbox"/>	Wafer Fab Process												
PCN Details															
Description of Change:															
<p>The purpose of this notification is to provide information on the leadframe die pad offset change for select devices on the Product Affected section. Details are provided below.</p>															
<table border="1"> <thead> <tr> <th></th> <th>From</th> <th>To</th> </tr> </thead> <tbody> <tr> <td>Leadframe Part No.</td> <td>4212077</td> <td>4221268</td> </tr> <tr> <td>Die Pad Offset</td> <td>0.008 inch</td> <td>0.00 inch</td> </tr> <tr> <td></td> <td style="text-align: center;">  </td> <td style="text-align: center;">  </td> </tr> </tbody> </table>					From	To	Leadframe Part No.	4212077	4221268	Die Pad Offset	0.008 inch	0.00 inch			
	From	To													
Leadframe Part No.	4212077	4221268													
Die Pad Offset	0.008 inch	0.00 inch													
															
Reason for Change:															
Standardize leadframe die pad offset design for Isolation devices															
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):															
None															
Anticipated impact on Material Declaration															
<input checked="" type="checkbox"/>	No Impact to the Material Declaration	<input type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI Eco-Info website . There is no impact to the material meeting current regulatory compliance requirements with this PCN change.												
Changes to product identification resulting from this PCN:															
None															
Product Affected:															
ISO7421MDREP		V62/16605-01XE													

Qualification Report

ISO1540D and ISO721MD families with Sumitomo LF 4221268

Approve Date 20-Nov-2015

Product Attributes

Attributes	Qual Device: ISO1540D	Qual Device: ISO721MD	QBS Package Reference: DAC7744EB	QBS Package Reference: INA2126E
Assembly Site	TAI	TAI	MLA	MLA
Package Family	SOIC	SOIC	SSOP	SSOP
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	DMOS5	DFAB	SFAB	HFAB/TFAB
Wafer Fab Process	50HPA07ISO	LBC4	JIBBC-HV7	635G

Attributes	QBS Package Reference: ISO1540D	QBS Package Reference: ISO1541D	QBS Package Reference: OPA2277U	QBS Package Reference: TPA2085D
Assembly Site	TAI	TAI	MLA	TAI
Package Family	SOIC	SOIC	SOIC	SOIC
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	DMOS5	DMOS5	HFAB/TFAB	DFAB
Wafer Fab Process	50HPA07ISO	50HPA07ISO	635G	LBC4

- QBS: Qual By Similarity
- Qual Device ISO1540D is qualified at LEVEL2-260C
- Device ISO1540D contains multiple dies.

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: ISO1540D	Qual Device: ISO721MD	QBS Package Reference: DAC7744EB	QBS Package Reference: INA2126E
AC	Autoclave 121C	96 Hours	-	-	1/77/0	1/77/0
FLAM	Flammability (IEC 695-2-2)	--	-	-	1/5/0	-
FLAM	Flammability (UL -1694)	--	-	-	1/5/0	-
FLAM	Flammability (UL 94V-0)	--	-	-	1/5/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	1/77/0	1/7/0
HTOL	Life Test, 125C	1000 Hours	-	-	1/77/0	1/77/0
HTOL	Life Test, 155C	240 Hours	-	-	-	-
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	-	1/77/0	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	-	-
LI	Lead Fatigue	Leads	1/22/0	1/22/0	-	-
LI	Lead Pull	Leads	1/22/0	1/22/0	-	-
SD	Surface Mount Solderability	Pb Free Solder	1/22/0	1/22/0	-	-
SD	Surface Mount Solderability.	Pb Solder	1/22/0	1/22/0	-	-
TC	Temperature Cycle, - 65/150C	500 Cycles	-	-	1/77/0	1/77/0

Type	Test Name / Condition	Duration	Qual Device: ISO1540D	Qual Device: ISO721MD	QBS Package Reference: DAC7744EB	QBS Package Reference: INA2126E
TS	Thermal Shock -65C/+150C	500 Cycles	-	-	-	-
WBP	Bond Pull	Wires	1/76/0	1/76/0	-	-
WBS	Ball Bond Shear	Wires	1/76/0	1/76/0	-	-

Type	Test Name / Condition	Duration	QBS Package Reference: ISO1540D	QBS Package Reference: ISO1541D	QBS Package Reference: OPA2277U	QBS Package Reference: TPA2085D
AC	Autoclave 121C	96 Hours	2/154/0	1/68/0	1/77/0	3/231/0
FLAM	Flammability (IEC 695-2-2)	--	-	-	1/5/0	-
FLAM	Flammability (UL - 1694)	--	-	-	1/5/0	-
FLAM	Flammability (UL 94V-0)	--	-	-	1/5/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	1/76/0	2/80/0
HTOL	Life Test, 125C	1000 Hours	-	-	1/77/0	-
HTOL	Life Test, 155C	240 Hours	-	-	-	2/80/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	-	1/77/0	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	-	3/231/0
LI	Lead Fatigue	Leads	-	-	-	-
LI	Lead Pull	Leads	-	-	-	-
SD	Surface Mount Solderability	Pb Free Solder	-	-	-	-
SD	Surface Mount Solderability.	Pb Solder	-	-	-	-
TC	Temperature Cycle, -65/150C	500 Cycles	2/154/0	1/77/0	1/77/0	3/231/0
TS	Thermal Shock -65C/+150C	500 Cycles	-	-	1/77/0	3/231/0
WBP	Bond Pull	Wires	1/76/0	1/76/0	-	-
WBS	Ball Bond Shear	Wires	1/76/0	1/76/0	-	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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USA	PCNAmericasContact@list.ti.com
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